Etching Fundamentals Workshop
University of Notre Dame
January 13, 2012 • 8am – 5pm

Plasma-Therm, one of leading manufacturers of plasma based etch and deposition equipment, will be presenting a one-day workshop on the fundamental of plasma etching, plasma reactors, and plasma etching mechanisms. The workshop will review state of the art etching technologies as applied to semiconductor, MEMS, and nanofabrication. The workshop is free of charge, and lunch will be provided.

<u>You must pre-register for this event by December 16, 2011.</u>
Send email to Maureen Metcalf (mmetcalf@nd.edu) with name, affiliation and contact information.

7:30 am – 8:00 am	Registration
8:00 am – 8:15 am	Welcome
8:15 am – 10:15 am	Basics: Vacuum, Plasma and Reactors
10:15 am – 10:30 am	*Break*
10:30 am – 11:30 am	Plasma Etching Mechanisms
11:30 am - 12:15 pm	Deep Silicon Etching
12:15 pm – 1:15 pm	Networking Lunch
1:15 pm – 2:15 pm	Compound Semiconductor Etching
2:15 pm – 3:15 pm	Dielectric Etching
3:15 pm – 3:30 pm	*Break*
3:30 pm – 4:15 pm	Metal Etching
4:15 pm – 5:00 pm	Endpoint Basics
5:00 pm – 6:00 pm	Q&A

The Instructors:

David Lishan received his Bachelor's degree in Chemistry from UC Santa Cruz and a Ph.D. from UC Santa Barbara in Solid State Electrical Engineering. During his career he has worked on a wide range of chemistry, semiconductor, and materials R&D projects that included projects in photochemistry, x-ray mask fabrication, PVD, and plasma processing. He joined Plasma-Therm 13 years ago and currently holds the positions of Principle Scientist and Director of Technical Marketing. His interests are in the application of plasma processing for MEMS, photonics, data storage, and compound semiconductor applications.

Chris Johnson received his Bachelor's degree in Materials Science and Engineering from the University of Florida in 2004. He joined Plasma-Therm in 2005 and currently works as an Applications Engineer II. While at Plasma-Therm he has worked in product development department focusing on R&D in processes and hardware for both plasma etch and PECVD systems. His experience includes DRIE, photomask, and III-V materials for etch, thin film dielectrics for PECVD, and optical endpoint techniques for both etch and PECVD.